imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SUBMINIATURE SOLID STATE LAMP

Part Number: AM2520ZGC09



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Features

- Subminiature package.
- Z-bend lead.
- Long life solid state reliability.
- Low package profile.
- Moisture sensitivity level : level 3.
- Package : 1000pcs / reel.
- RoHS compliant.

Package Dimensions

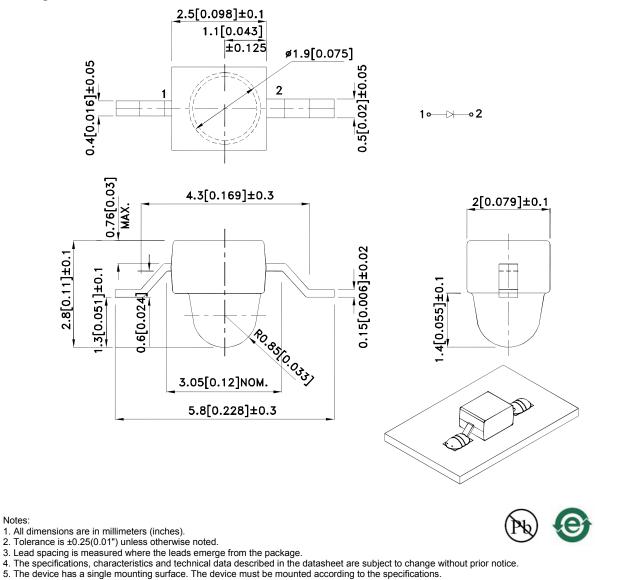
Description

The Green source color devices are made with InGaN on Sapphire Light Emitting Diode.

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.



SPEC NO: DSAH3717 APPROVED: WYNEC REV NO: V.6B CHECKED: Allen Liu DATE: JAN/08/2013 DRAWN: Y.Liu

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Selection Guide

| Part No. | Dice | Lens Type Iv (mcd) [2] @ 20mA | | / - - | Viewing Angle [1] | |
|-------------|---------------|----------------------------------|------|--------------|----------------------|--|
| | | | Min. | Тур. | 201/2 | |
| AM2520ZGC09 | Green (InGaN) | Water Clear | 1900 | 3000 | 20° | |

Notes:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.
3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

| Symbol | Parameter | Device | Тур. | Max. | Units | Test Conditions | |
|--------|--------------------------|--------|------|------|-------|-----------------|--|
| λpeak | Peak Wavelength | Green | 515 | | nm | IF=20mA | |
| λD [1] | Dominant Wavelength | Green | 525 | | nm | IF=20mA | |
| Δλ1/2 | Spectral Line Half-width | Green | 30 | | nm | IF=20mA | |
| С | Capacitance | Green | 45 | | pF | VF=0V;f=1MHz | |
| VF [2] | Forward Voltage | Green | 3.3 | 4.1 | V | I⊧=20mA | |
| lr | Reverse Current | Green | | 50 | uA | Vr=5V | |

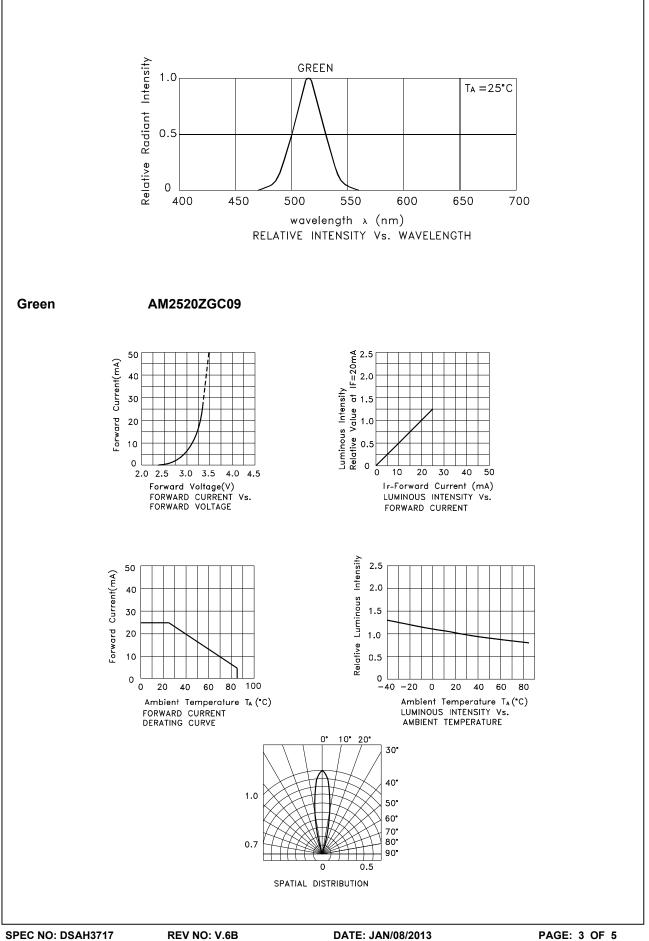
Notes:

Wavelength: +/-1nm.
 Forward Voltage: +/-0.1V.
 Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

| Parameter | Green | Units | |
|--------------------------|----------------|-------|--|
| Power dissipation | 102.5 | mW | |
| DC Forward Current | 25 | mA | |
| Peak Forward Current [1] | 150 | mA | |
| Reverse Voltage | 5 | V | |
| Operating Temperature | -40°C To +85°C | | |
| Storage Temperature | -40°C To +85°C | | |

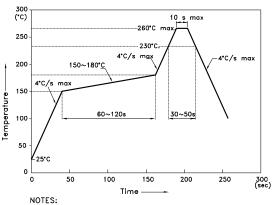
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.



AM2520ZGC09

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.

